

# **Dual P-Channel -20 V (D-S) MOSFET**

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)		
	$0.65 \text{ at V}_{GS} = -4.5 \text{ V}$	-0.30			
-20	0.84 at V <sub>GS</sub> = -2.5 V	-0.25	0.75		
	1.20 at V <sub>GS</sub> = -1.8 V	-0.18			

#### **FEATURES**

- TrenchFET<sup>®</sup> Power MOSFET
- 100 % R<sub>g</sub> Tested
- Gate-Source ESD Protected: 1000 V

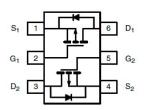


RoHS

#### **APPLICATIONS**

- Load/Power Switching for Portable Devices
- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories
- Battery Operated Systems
- Power Supply Converter Circuits

#### SC-75-6



Top View

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>A</sub> = 25 °C, unless otherwise noted)					
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		$V_{DS}$	-20	V	
Gate-Source Voltage		$V_{GS}$	± 12	v	
Continuous Drain Current /T 150 °C\a	T <sub>A</sub> = 25 °C	l <sub>a</sub>	-0.30 <sup>a, b</sup>		
Continuous Drain Current $(T_J = 150  ^{\circ}C)^a$	T <sub>A</sub> = 70 °C	ID	-0.15 <sup>a, b</sup>	A	
Pulsed Drain Current		I <sub>DM</sub>	-2		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	-0.18 <sup>a, b</sup>	A	
Maniana Dama Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	0.22 <sup>a, b</sup>	w	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 70 °C	l 'D	0.14 <sup>a, b</sup>	vv	
Operating Junction and Storage Temperature Ra	inge	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Тур.	Max.	Unit
Maximum Junction-to-Ambient <sup>b</sup>	t ≤ 5 s	R <sub>thJA</sub>	470	565	°C/W
waximum junction-to-Ambient	Steady State	r inJA	560	675	O/ <b>VV</b>

#### Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 5 s.



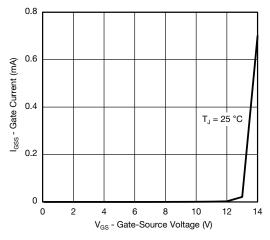
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static					l.		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-20			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050 A		-17		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = -250 μA		- 1.8			
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-0.5		-1.5	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 30		
Gate-Source Leakage		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$			± 1	<b>^</b>	
Zero Gate Voltage Drain Current	-	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}$			-1	<u>μ</u> Α	
Zero Gate voltage Drain Current	I <sub>DSS</sub>	$V_{DS}$ = -20 V, $V_{GS}$ = 0 V, $T_{J}$ = 85 °C			-3		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$_{DS}$ = $\geq$ -5 V, $V_{GS}$ = -4.5 V	-2			Α	
		$V_{GS} = -4.5 \text{ V}, I_D = -0.3 \text{A}$		0.650			
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = -2.5 V, I <sub>D</sub> = -0.25A		0.840		Ω	
	20(0)	V <sub>GS</sub> = -1.8 V, I <sub>D</sub> = -0.18A		1.20		-	
Forward Transconductance	9 <sub>fs</sub>	$V_{DS} = -10 \text{ V}, I_D = -0.3 \text{A}$		7.5		S	
Dynamic <sup>b</sup>				L		l	
Input Capacitance	C <sub>iss</sub>			120			
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		14		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			8		1	
Total Cata Charge	Q <sub>g</sub> -	$V_{DS} = -10 \text{ V}, V_{GS} = -8 \text{ V}, I_{D} = -0.3 \text{ A}$		1.3	2	nC	
Total Gate Charge				0.75	1.2		
Gate-Source Charge		$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = 0.3 \text{ A}$		0.15			
Gate-Drain Charge	Q <sub>gd</sub>			0.13		1	
Gate Resistance	R <sub>g</sub>	f = 1 MHz	2.4	12.2	24.4	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			11	20		
Rise Time	t <sub>r</sub>	$V_{DD}$ = -10 V, $R_L$ = 20 $\Omega$		16	24	ns	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 0.5 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		26	39		
Fall Time	t <sub>f</sub>			11	20		
<b>Drain-Source Body Diode Characterist</b>	ics					,	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				-2	Α	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> =- 0.3 A		-0.8	-1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			10	15	ns	
Body Diode Reverse Recovery Charge	Q			2	4	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	I <sub>F</sub> = 0.5 A, dl/dt = 100 A/μs		5			
Reverse Recovery Rise Time	t <sub>b</sub>			5		ns	

- a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %. b. Guaranteed by design, not subject to production testing.

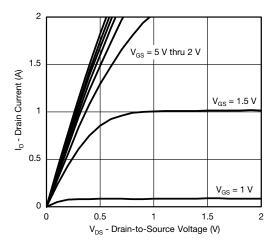
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



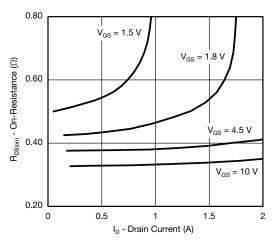
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



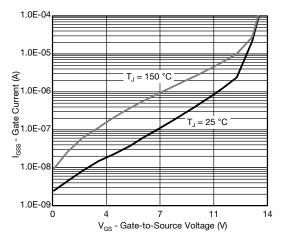
Gate Current vs. Gate-Source Voltage



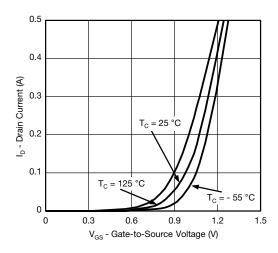
**Output Characteristics** 



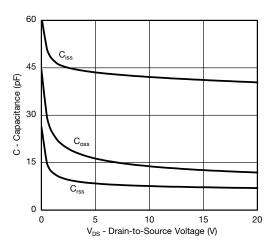
On-Resistance vs. Drain Current



Gate Current vs. Gate-Source Voltage



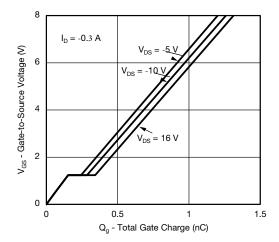
**Transfer Characteristics** 



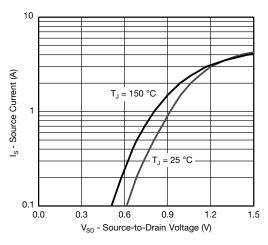
Capacitance



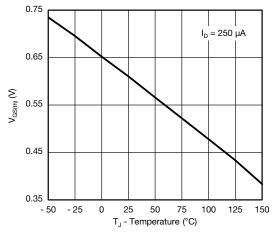
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



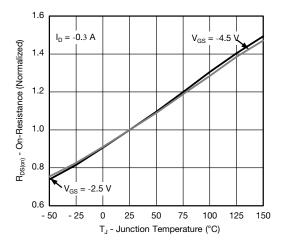
#### **Gate Charge**



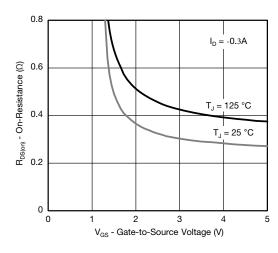
**Soure-Drain Diode Forward Voltage** 



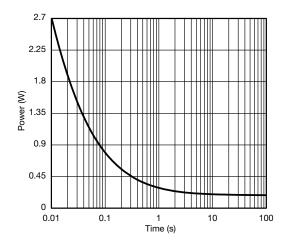
Threshold Voltage



On-Resistance vs. Junction Temperature



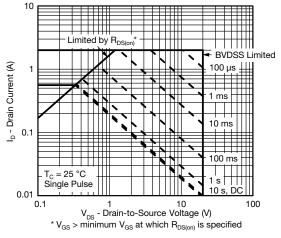
On-Resistance vs. Gate-to-Source Voltage

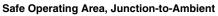


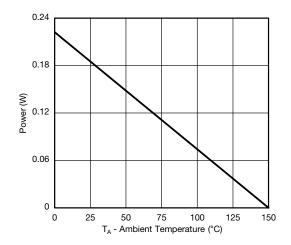
Single Pulse Power, Junction-to-Ambient



#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

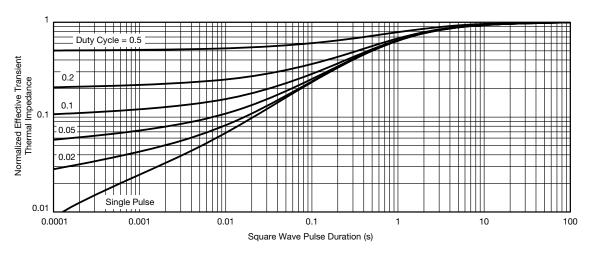






Power Derating, Junction-to-Ambient

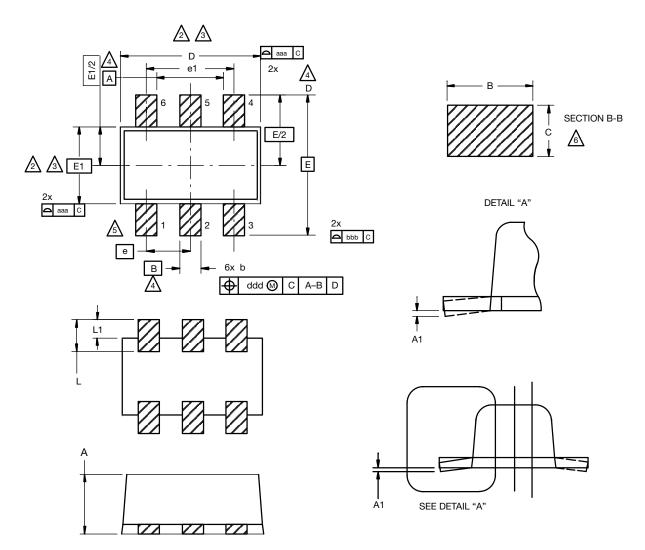
<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



Normalized Thermal Transient Impedance, Junction-to-Ambient



## SC-75-6



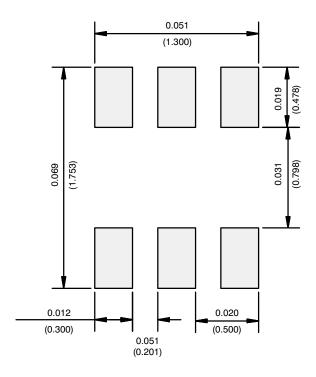
#### Notes

- 1. Dimensions in millimeters.
- Dimension D does not include mold flash, protrusions or gate burrs. Mold flush, protrusions or gate burrs shall not exceed 0.15 mm per dimension E1 does not include interlead flash or protrusion, interlead flash or protrusion shall not exceed 0.15 mm per side.
- 3. Dimensions D and E1 are determined at the outmost extremes of the plastic body exclusive of mold flash, the bar burrs, gate burrs and interlead flash, but including any mismatch between the top and the bottom of the plastic body.
- 4. Datums A, B and D to be determined 0.10 mm from the lead tip.
- 5. Terminal numbers are shown for reference only.
- These dimensions apply to the flat section of the lead between 0.08 mm and 0.15 mm from the lead tip.

DIM.	MILLIMETERS				
	MIN.	NOM.	MAX.		
Α	0.56	0.58	0.60		
A1	0	0.02	0.10		
b	0.15	0.22	0.30		
С	0.10	0.14	0.18		
D	1.50	1.60	1.70		
E	1.50	1.60	1.70		
E1	1.15	1.20	1.25		
е	0.45	0.50	0.55		
e1	0.95	1.00	1.05		
L	0.25	0.35	0.50		
L1	0.10	0.20	0.30		



### **RECOMMENDED MINIMUM PADS FOR SC-75-6: 6-Lead**



Recommended Minimum Pads Dimensions in Inches/(mm)

7



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